

Distributed Sniffer Nodes for Batteryless Sensor Nodes (sdmay24-25)

Website



Team Lead/ Software Lead: Thomas Gaul
Hardware Lead: Tori Kittleson
Hardware Member: Matthew Crabb
Software Member: Spencer Sutton
Scribe/Software Member: Ian Hollingworth

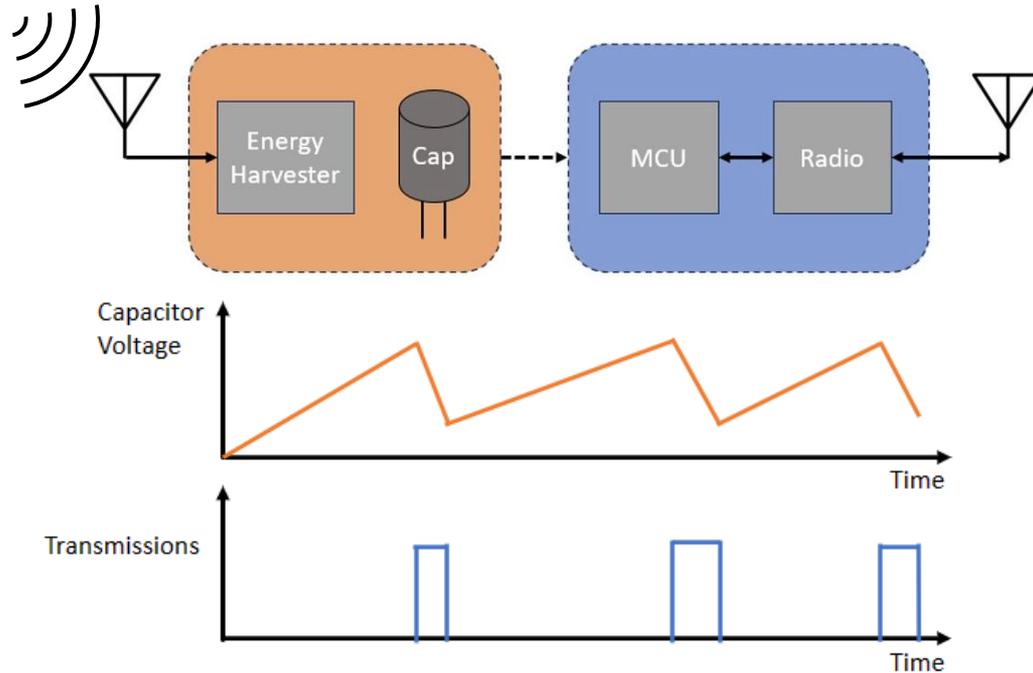
Advisor/Client: Henry Duwe
CPRE/EE 492 Spring 2024

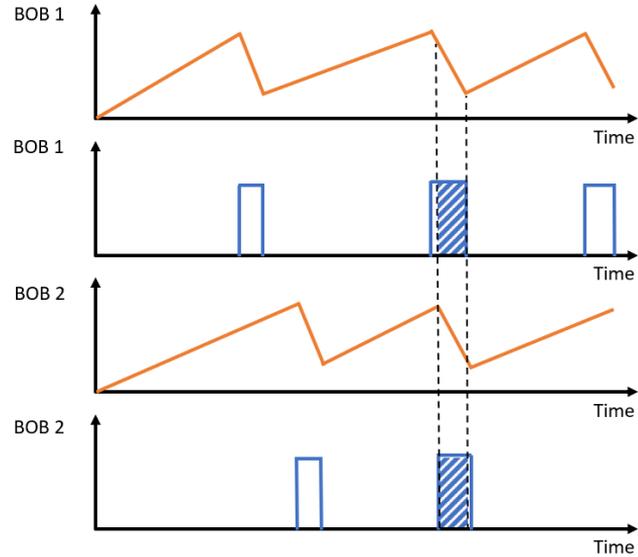
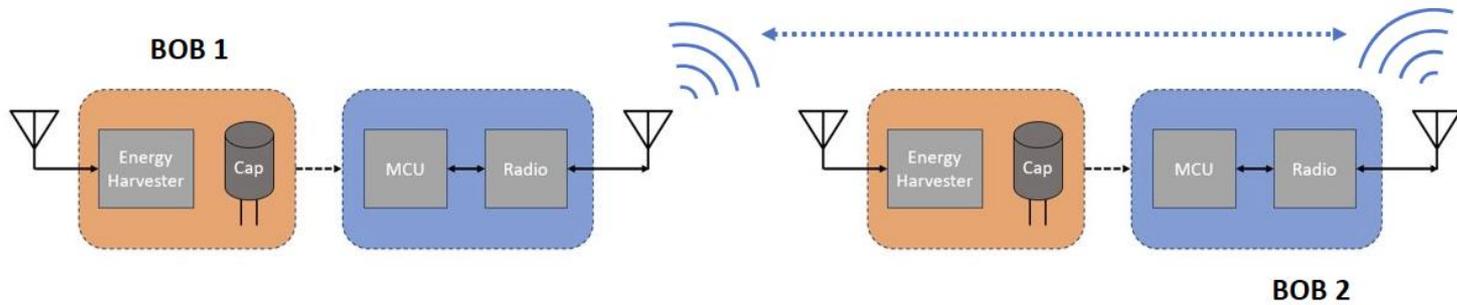
<https://sdmay24-25.sd.ece.iastate.edu/>

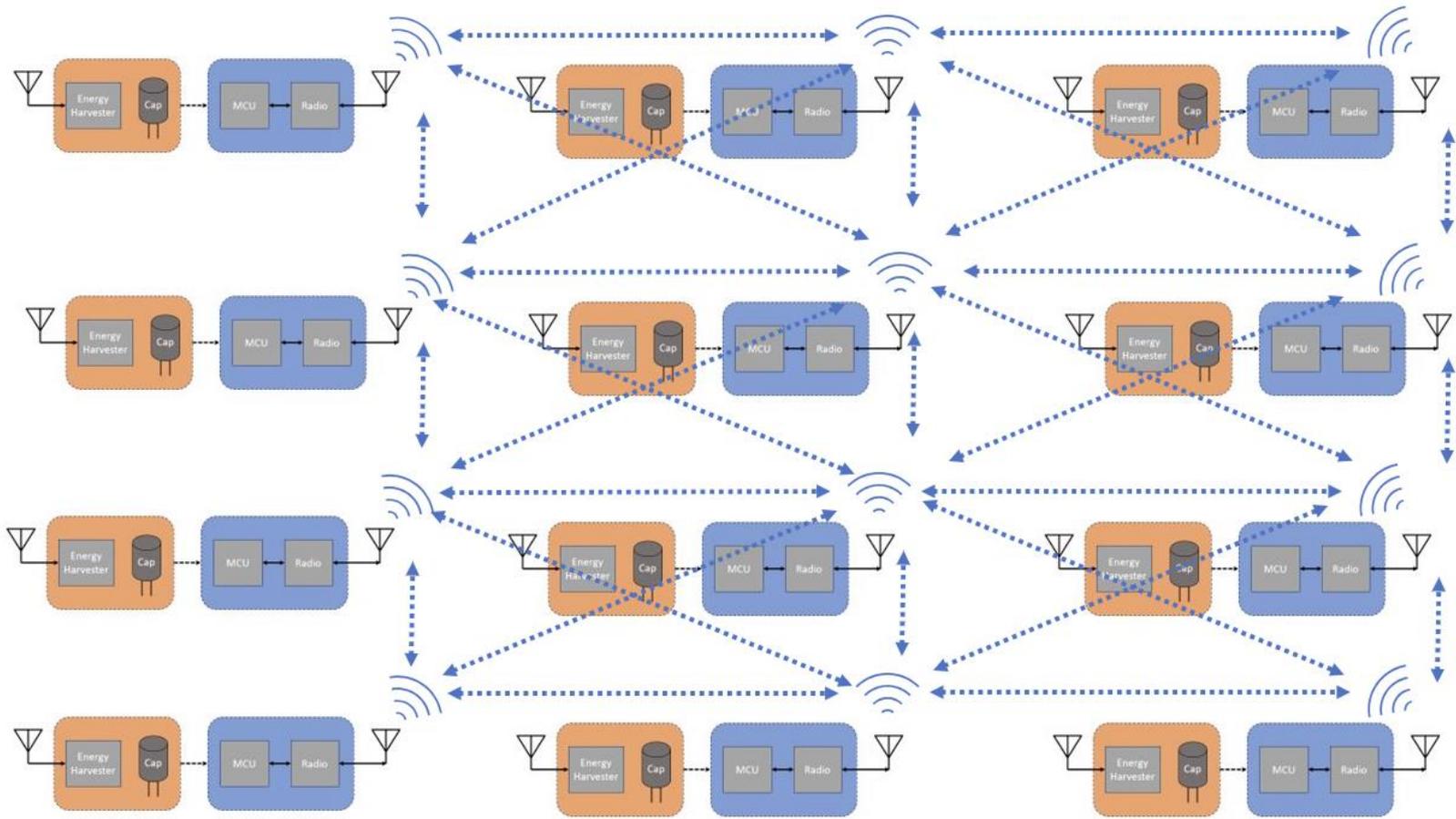
IOWA STATE UNIVERSITY

Project Overview

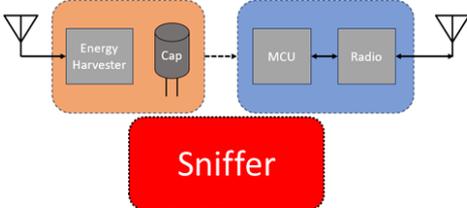
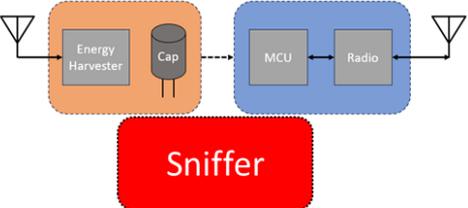
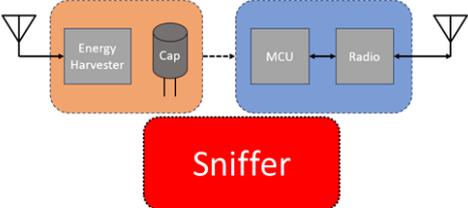
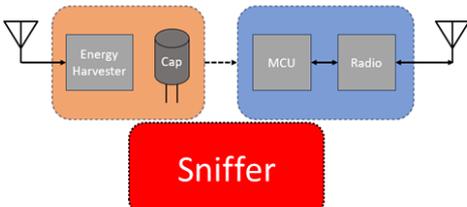
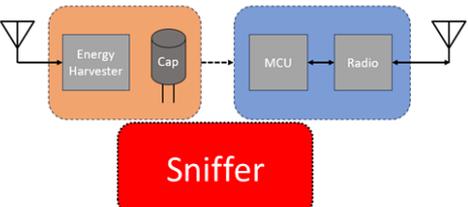
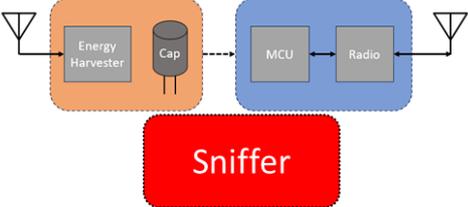
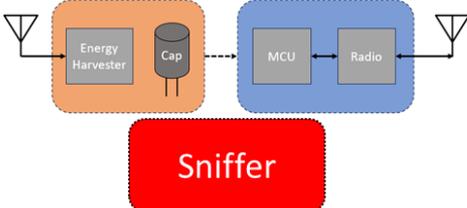
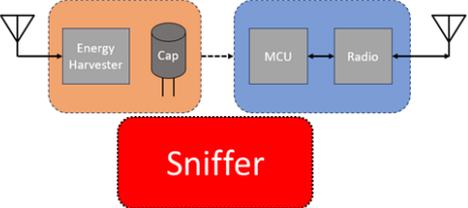
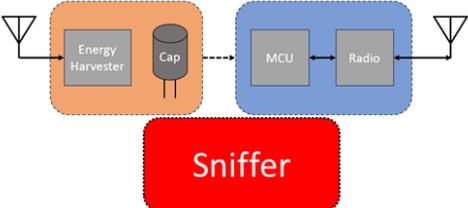
BOB Node - Batteryless sensor designed by client.







Goal: Create testbed for researchers to use for the batteryless nodes they are developing.



Use Cases

Scenario Node Tests

- Single node experiments
- Multi-node and single lab experiments
- Large scale testing (goal of 100 – 1000)

Users

- Dr. Duwe's research group
- Universities, companies, hobbyists through open-source nature

Potential Impact

- Factory condition monitoring
- Weather monitoring and recording
- Forest fire detection in national parks

Requirements

Functional

- 9 BOB/Sniffer pairs
- Sink Sniffer Node with continuous power
- Host system to organize and store Sniffer logs
- Sniffer Nodes powered for one week
- Sniffer Nodes inflict minimal effects on BOB Nodes
- BOB Nodes electrically isolated from one another
- Modular stack of BOB and Sniffer custom boards

Non-functional

- Scalable for a potential larger (100+ node) design
- Documentation
- Mechanical durability of system

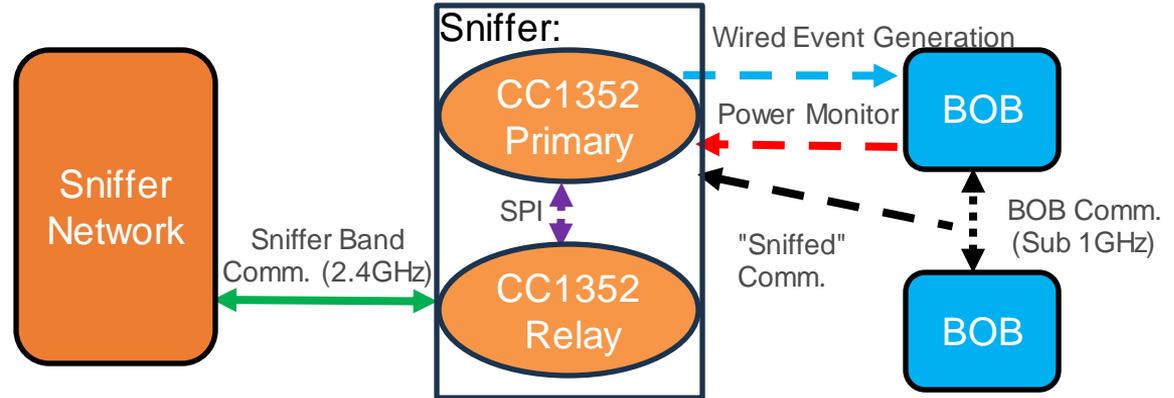
Deliverables

- Breakout Board Hardware
- MSP Simplified Hardware
- Sniffer Node Hardware
- Sniffer Node Software
- Open-Source Documentation
- Mechanically Sound System

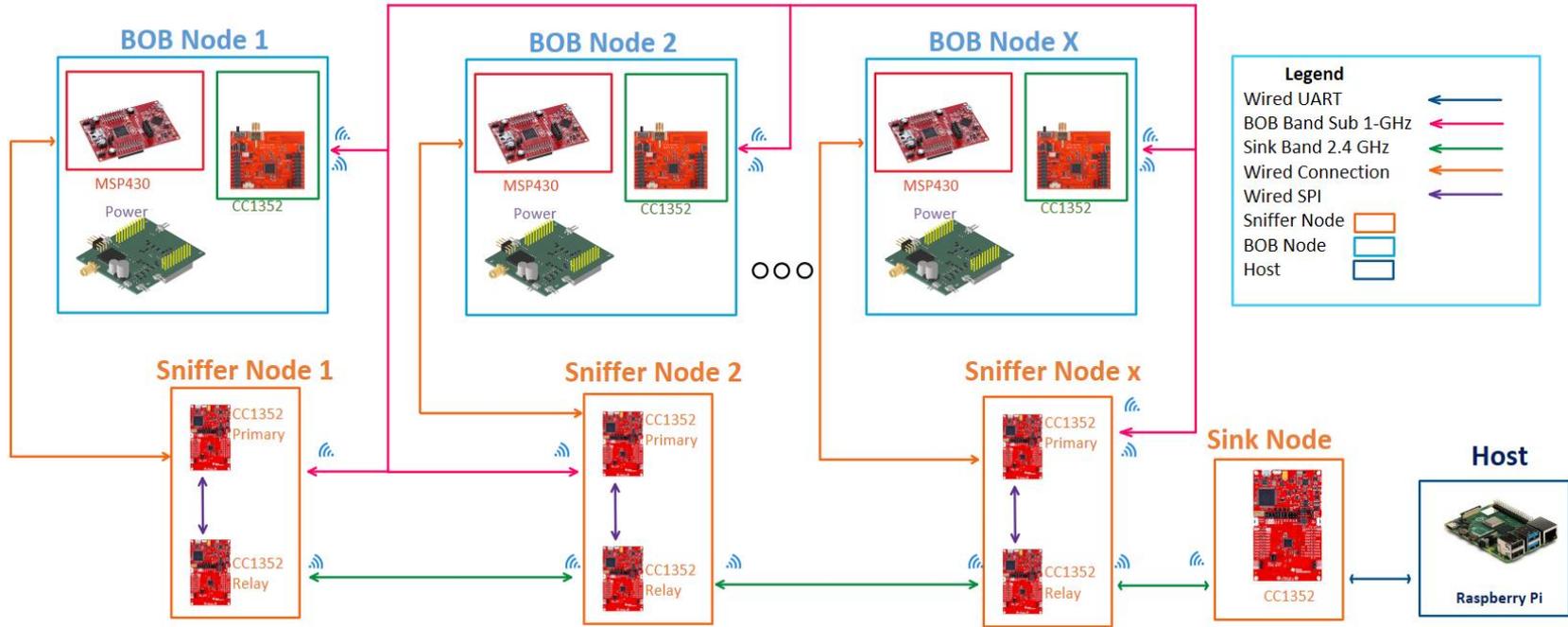
Sniffer Design

Tasks

- Monitor BOB status via GPIO
- Generate events for BOB via GPIO
- Monitor BOB radio communication
- Send test data to be saved

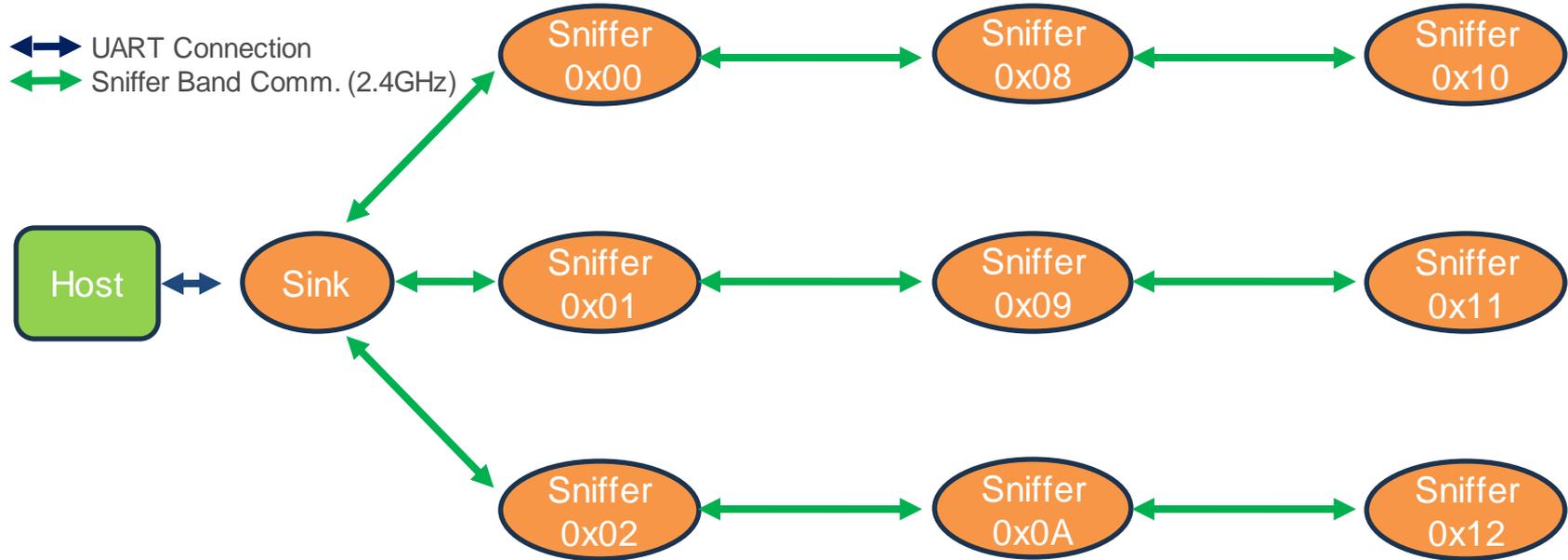


System Design



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System Design

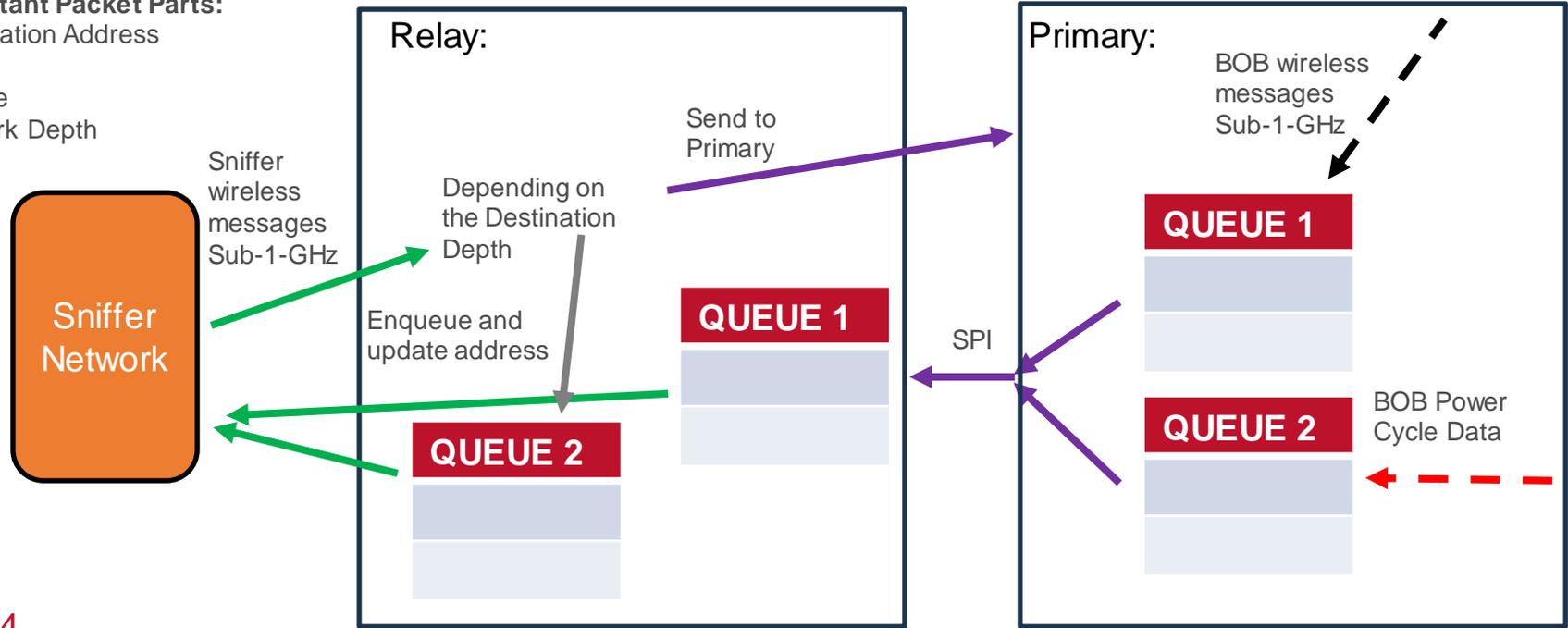


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Software Design

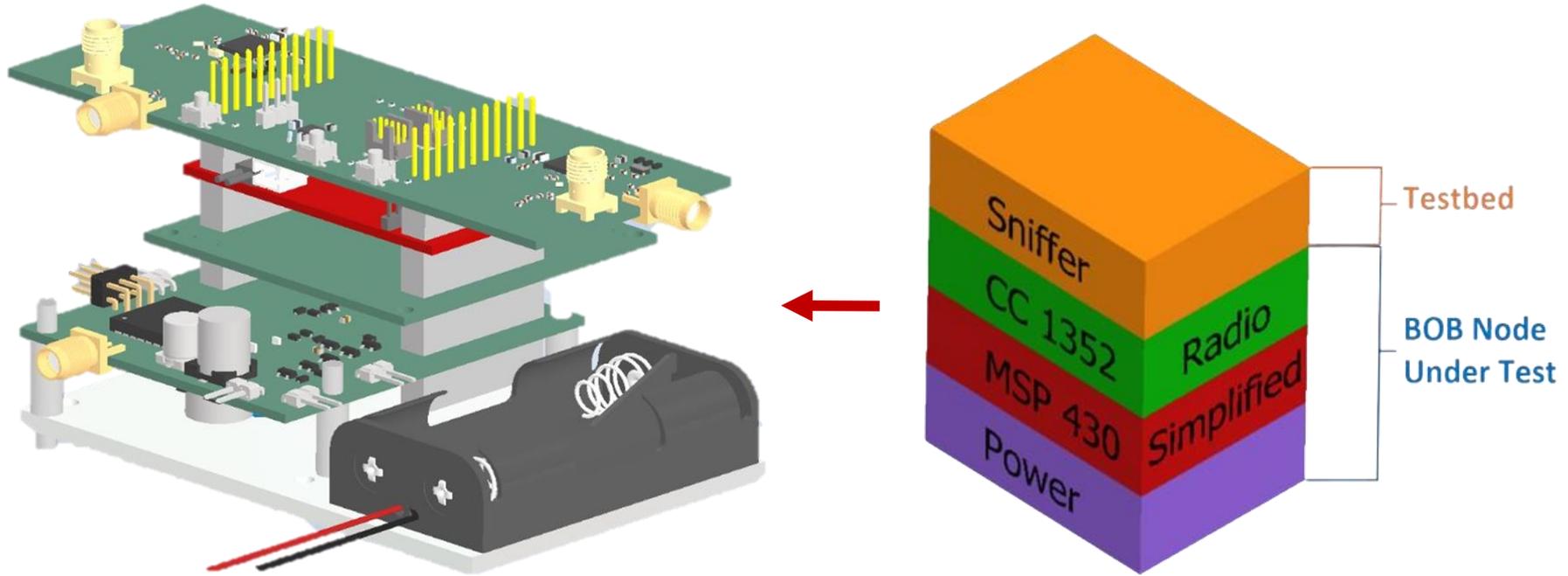
Important Packet Parts:

Destination Address
Type
Source
Network Depth
Data

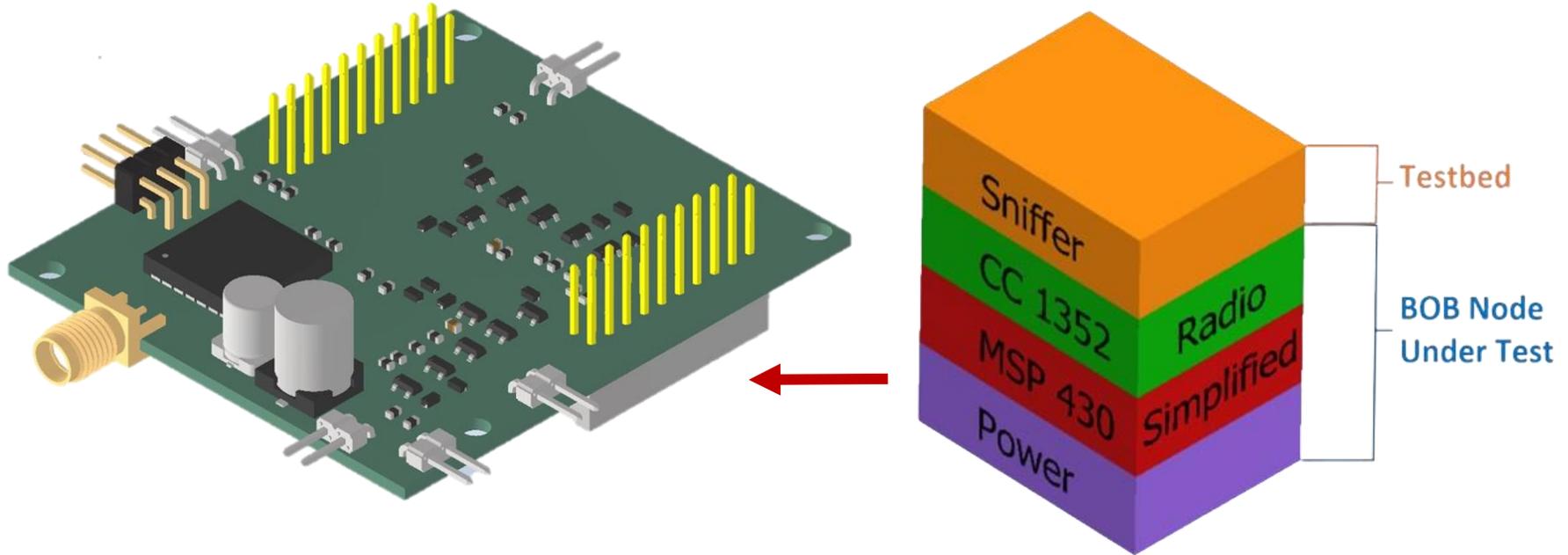


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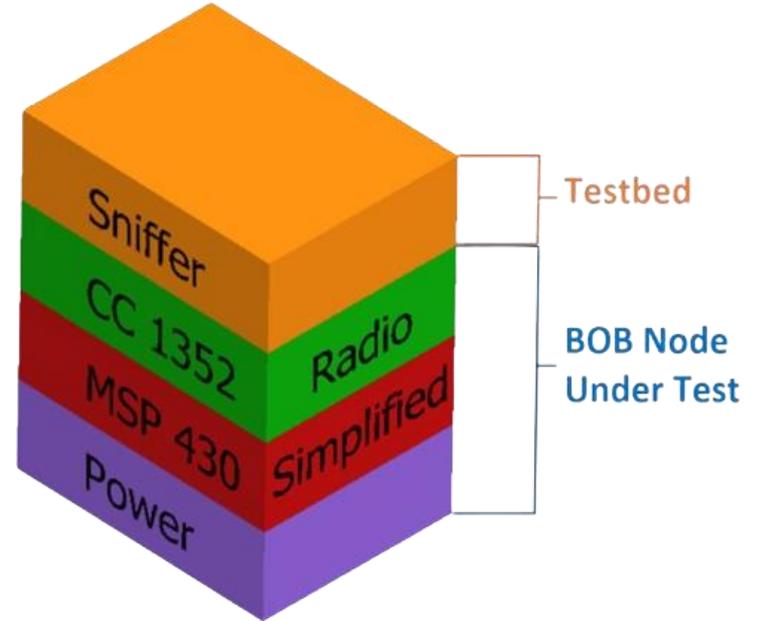
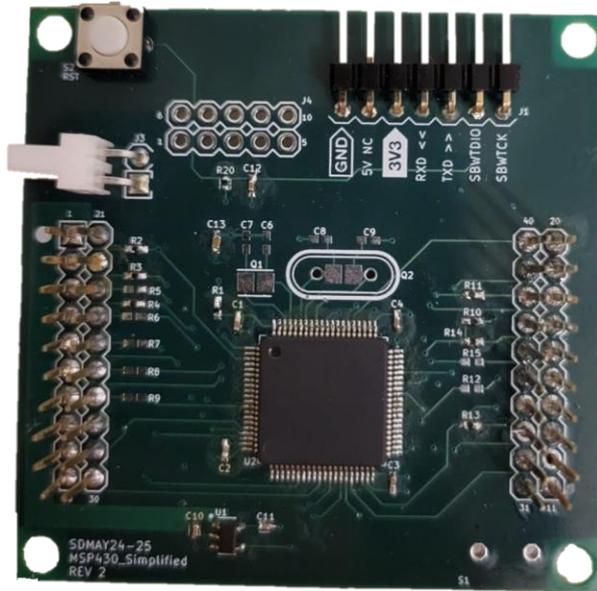
System Physical Design – PCB Stackup and Mounting



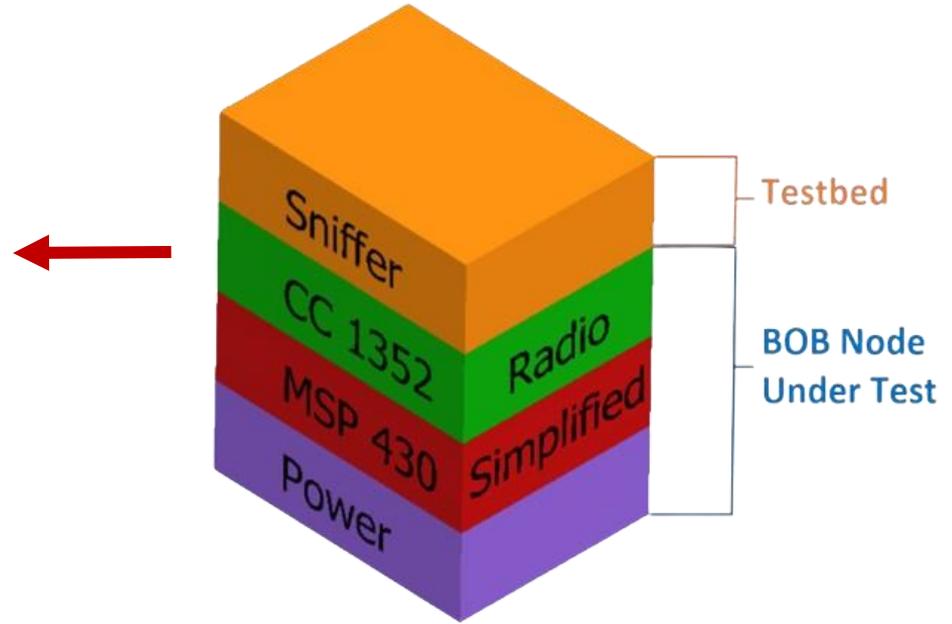
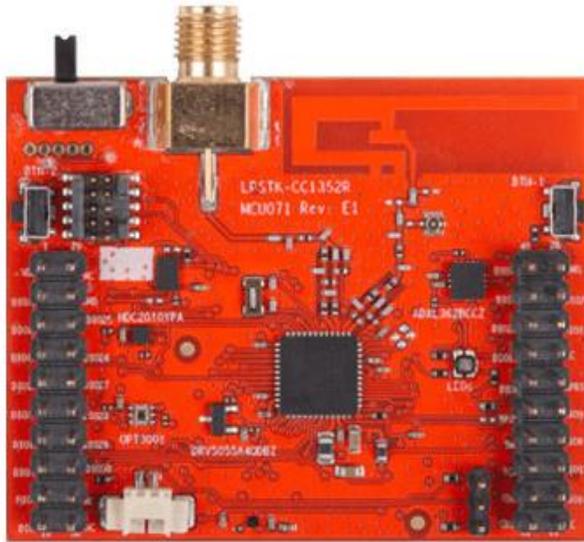
System Physical Design – Power Harvester PCB



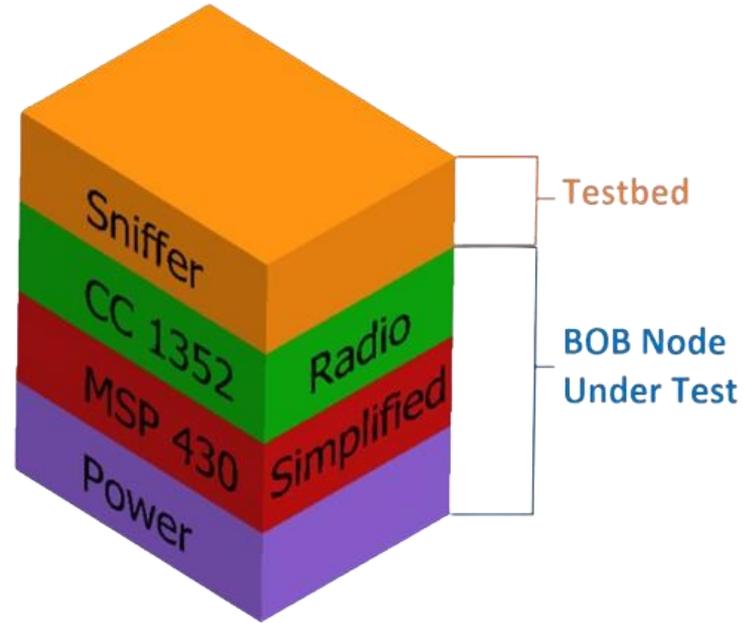
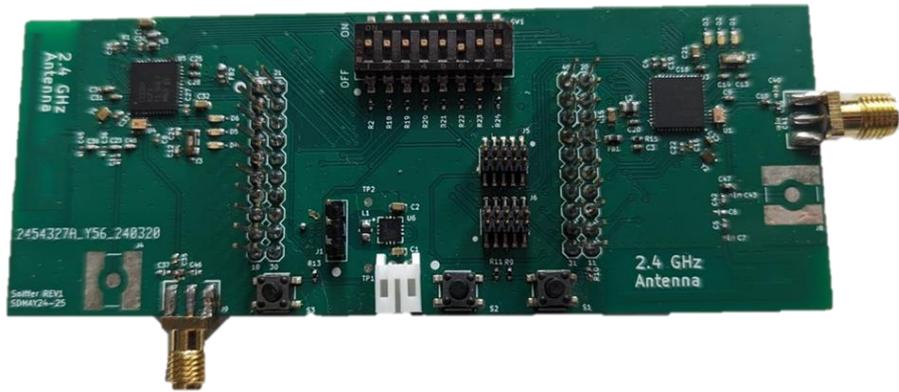
System Physical Design – MSP430 Simplified PCB



System Physical Design – CC1352 Radio PCB



System Physical Design – Sniffer PCB



Sniffer PCB Design – Battery System

Chose to use rechargeable NiMH AA batteries

Pros:

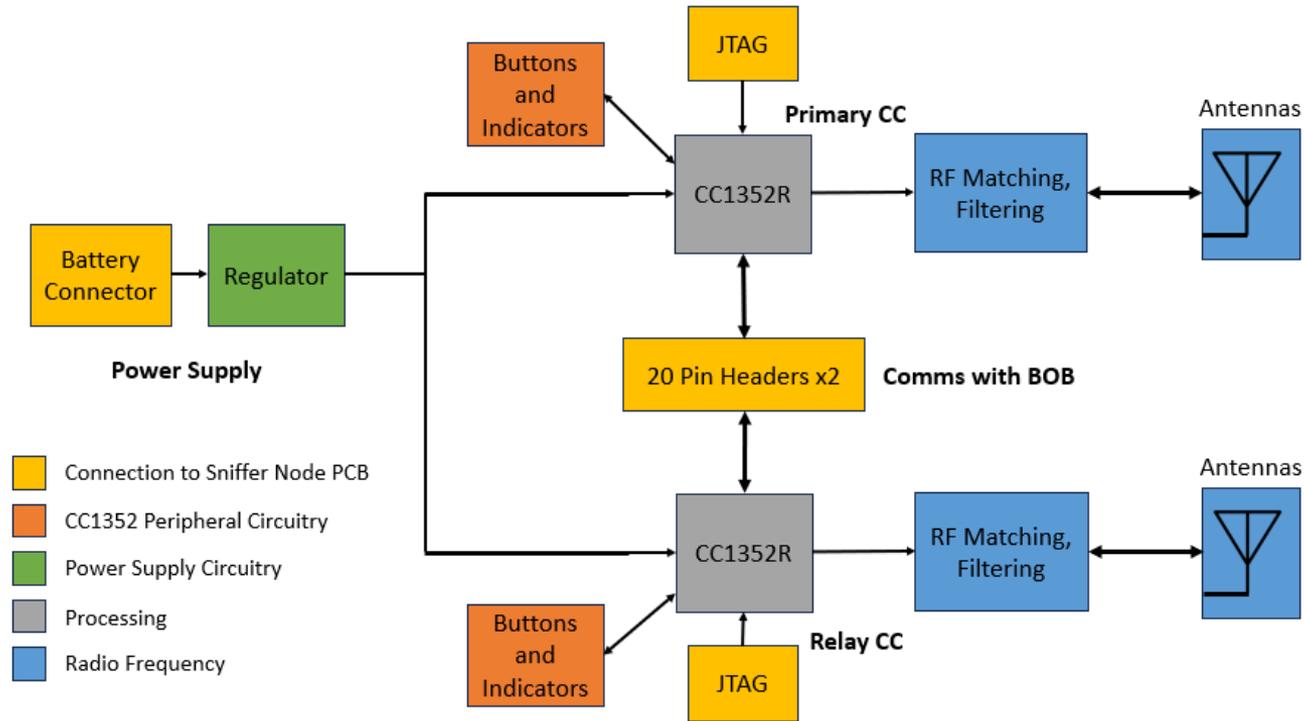
- Standard size, widely available
- Rechargeable 1,000x
- Simple, low-cost mounting solutions
- Multiple manufacturers
- Off the shelf or custom charging solutions
- Flexibility

Cons:

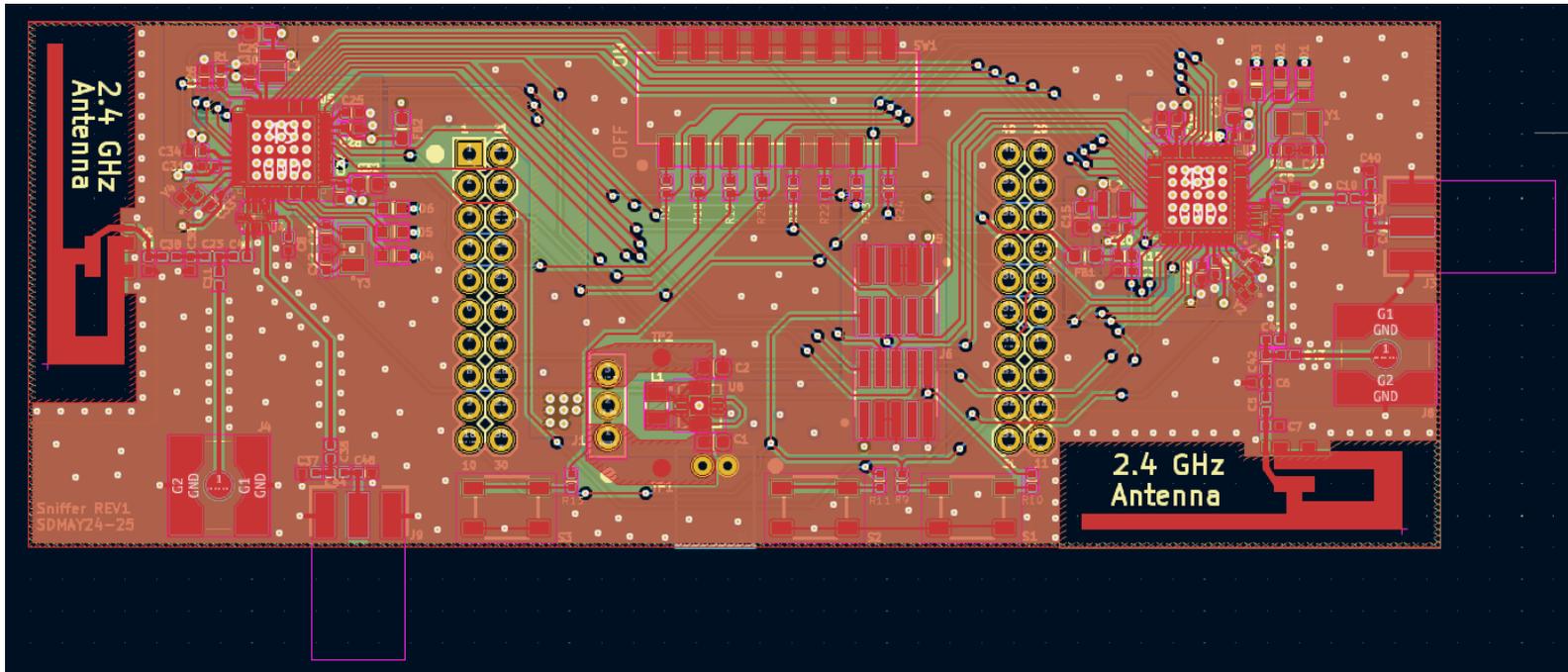
- Lower capacity than some other options
- Charging, protection, fuel gauge ICs not as widely available



Sniffer PCB Design – Block Diagram



Sniffer PCB Design – KiCad Layout



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Costs

Senior Design Cost Breakdown		
Item	Cost Per Node	Overall Cost
Breakout Board	-	\$37.83
MSP_Simplified	~\$31	\$234.60
Sniffer Board	~\$56	\$611.88
Batteries and Chargers	~\$12	\$112.05
Additional parts	-	\$29.29
Mechanical Design	~\$4	\$34.60
Total	~\$103	\$1060.25

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Testing

Unit Test

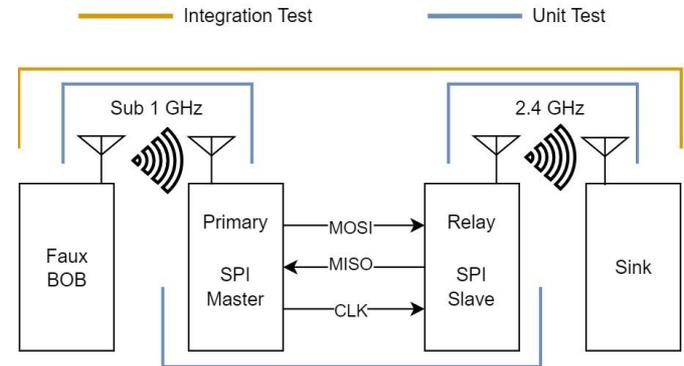
- SPI communication, Sub 1GHz communication, and 2.4 GHz Communication
- Electrical continuity and power checks
- Programming boards

Integration Tests

- SPI with Sub 1GHz and 2.4 GHz communication
- Software with custom hardware

System wide

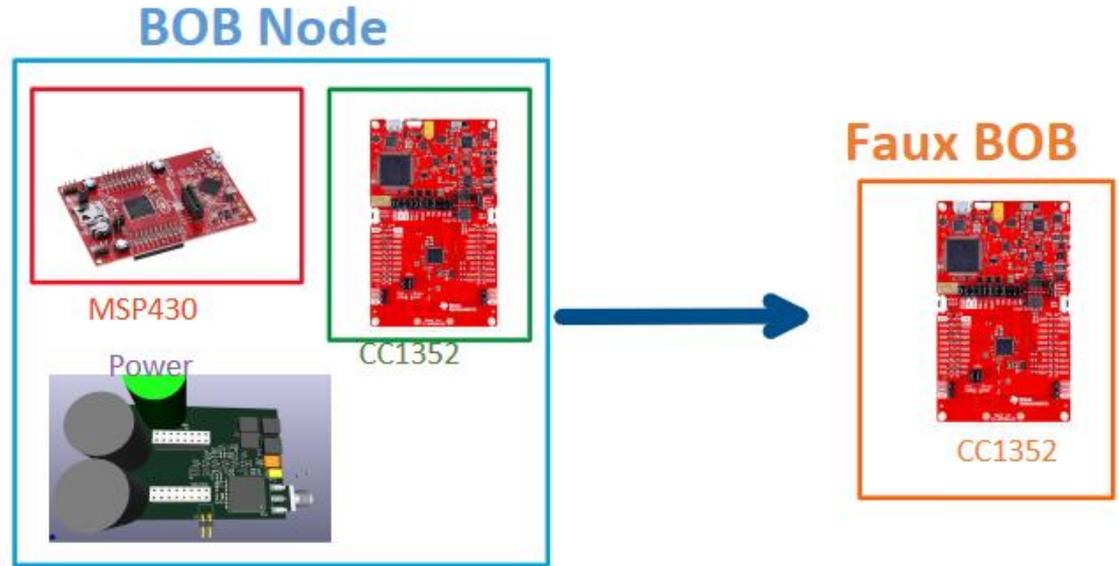
- Data transfer between multiple nodes



Faux BOB

Goal

- Create a test tool
- Emulate BOB functionality
- Allows us to have a known test



RF Testing and Tuning

Initial Plan

- Use a spectrum analyzer to tune the internal CC1352R load capacitors
- Ignore Sub-1GHz matching (all components assumed to have 50Ω ref impedance)
- Extract S-parameter information from 2.4GHz PCB antenna using a VNA and match

Problem

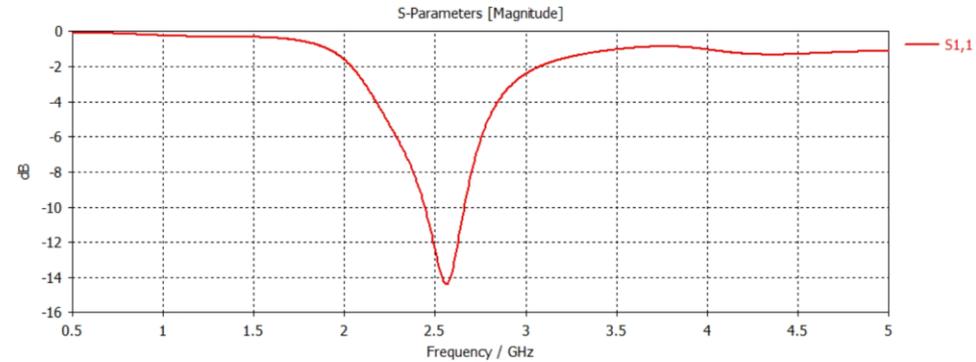
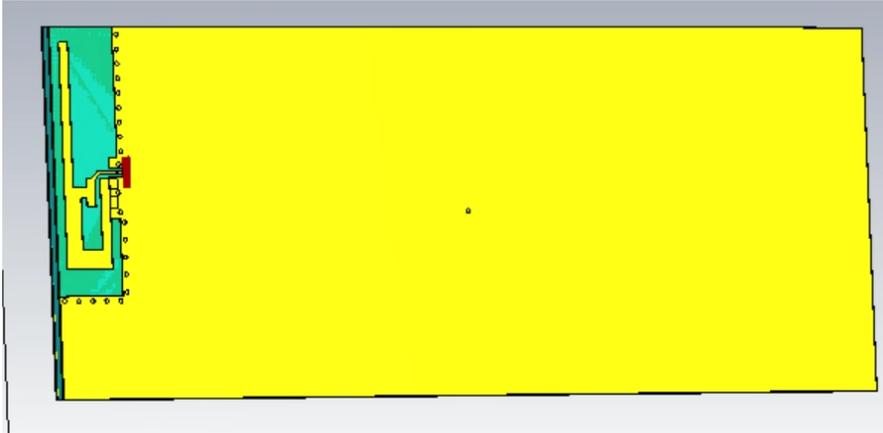
- Using equipment requires supervision + approval – could not get access until too late

Solution

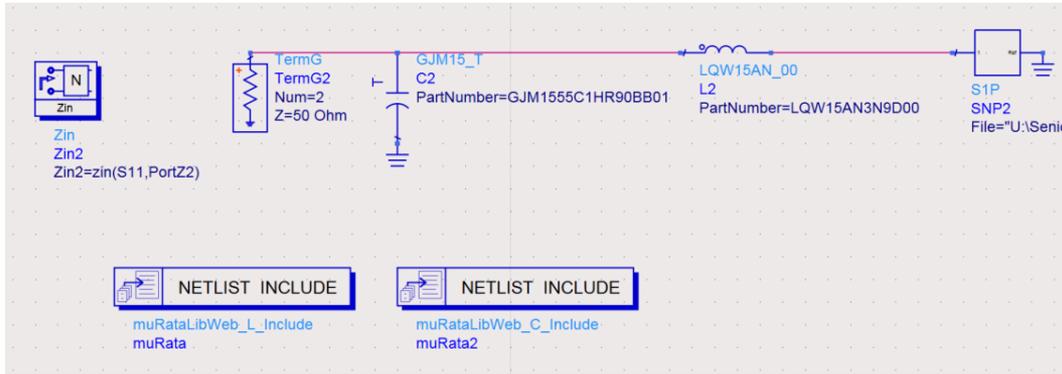
- Model antenna on the computer and simulate its operation
- Use simulation tools to find correct matching values

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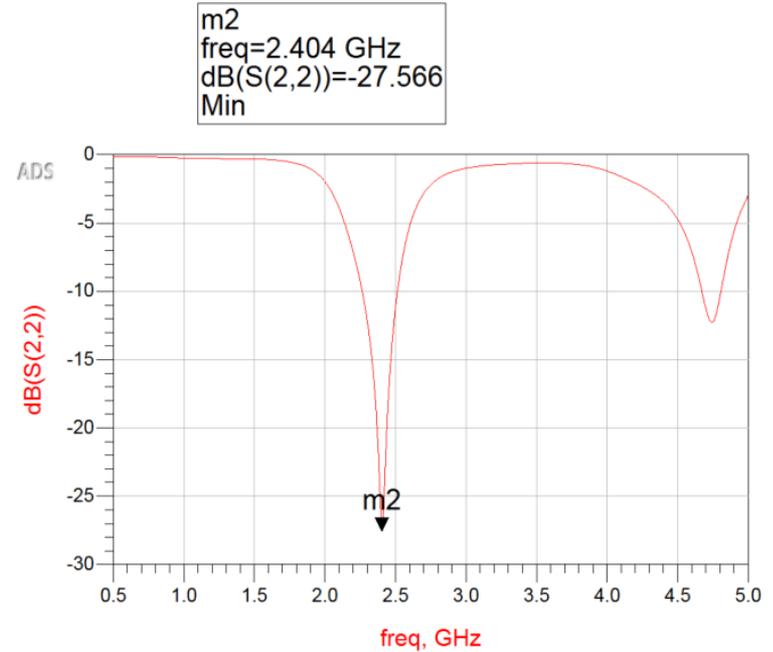
RF Testing and Tuning



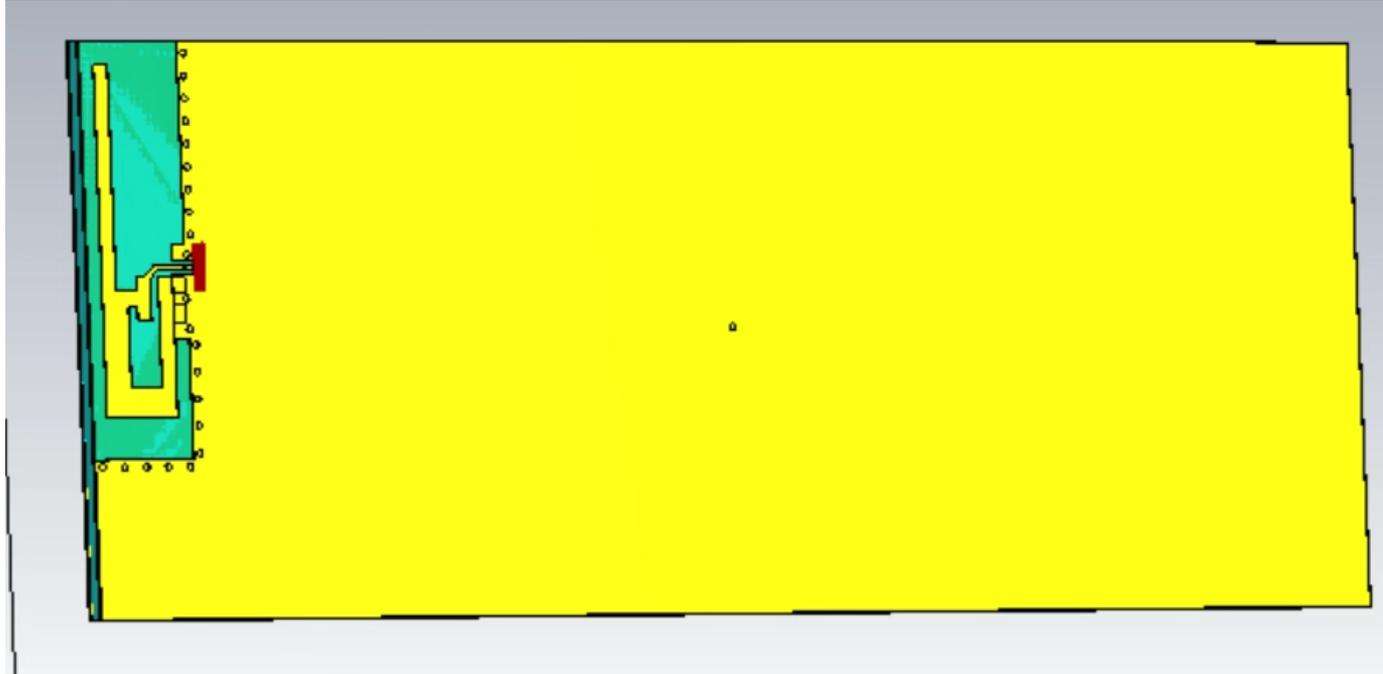
RF Testing and Tuning



freq	S(2,2)	Zin2
2.400 GHz	-27.138 / -80.493	50.000 + j0.001

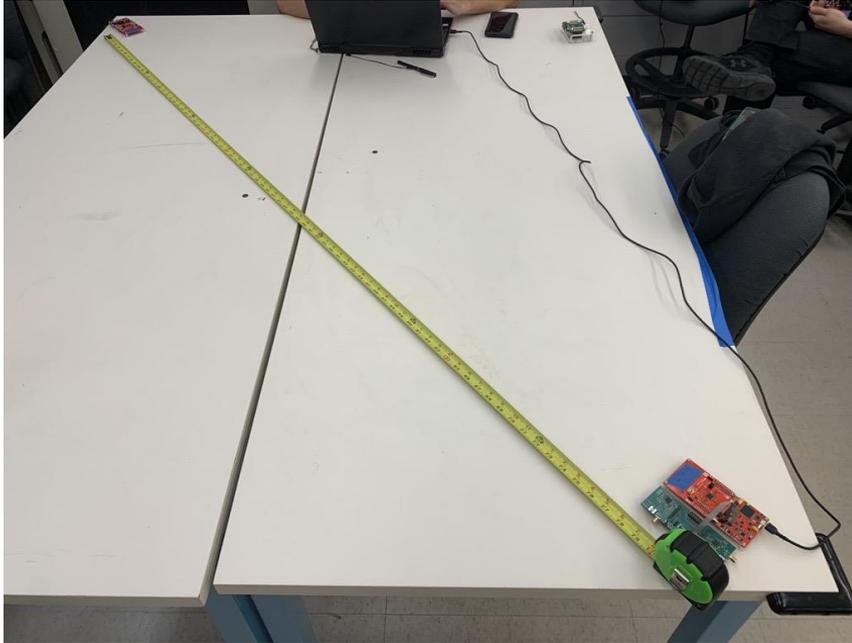


RF Testing and Tuning



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Radio Testing with TI SmartRF Studio

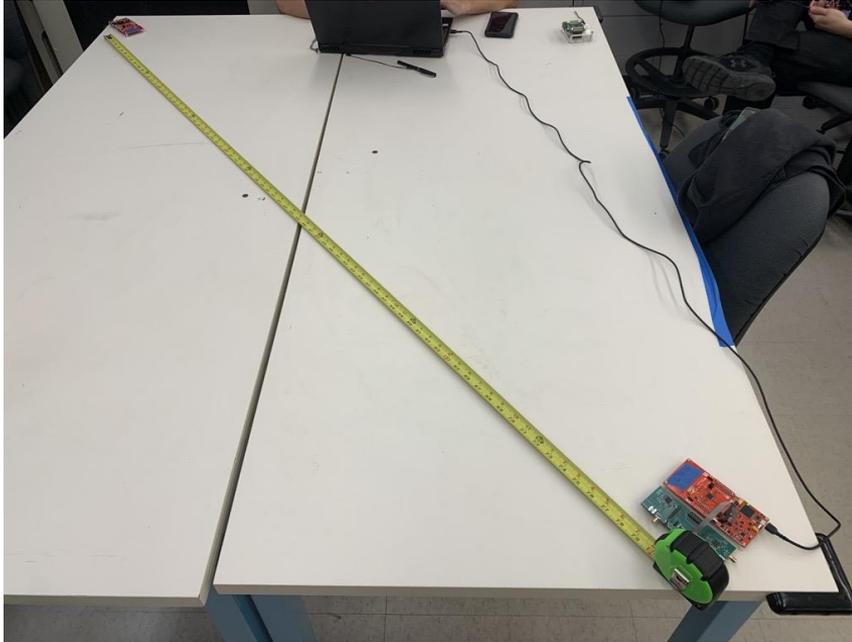


2.4GHz Wireless Testing

Test Configuration	RSSI (dBm)
REF1 → REF2	-52.7
REF1 ← REF2	-53.7
Sniffer (1) → REF2	-53.1
Sniffer (1) ← REF2	-53.1

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Radio Testing with TI SmartRF Studio

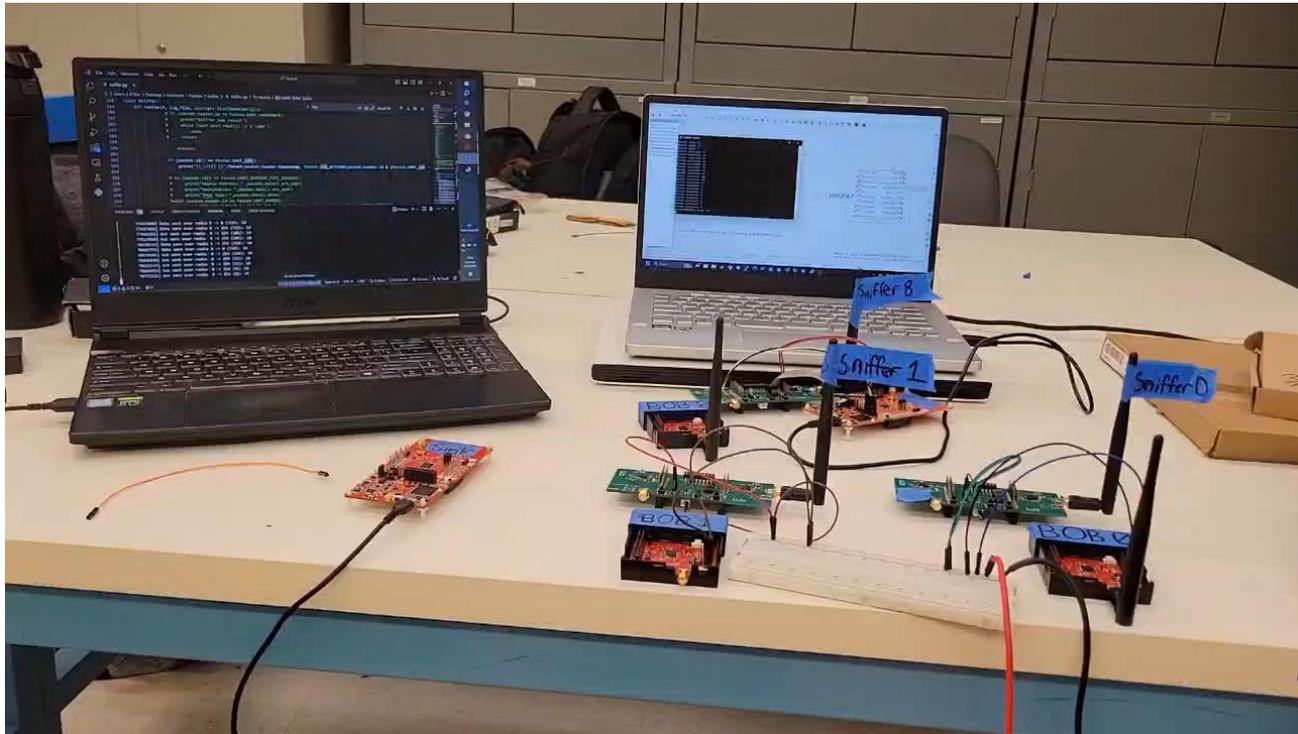


Sub-1GHz Wireless Testing

Test Configuration	RSSI (dBm)
REF1 → REF2	-31.9
REF1 ← REF2	-39.8
Sniffer (1) → REF2	-80.2
Sniffer (1) ← REF2	-80.8
Sniffer (2) → REF2	-39.2
Sniffer (2) ← REF2	-33.4

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Demo



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Challenges & Lessons Learned

Hardware

- RF design
- Multiple PCBs

Software

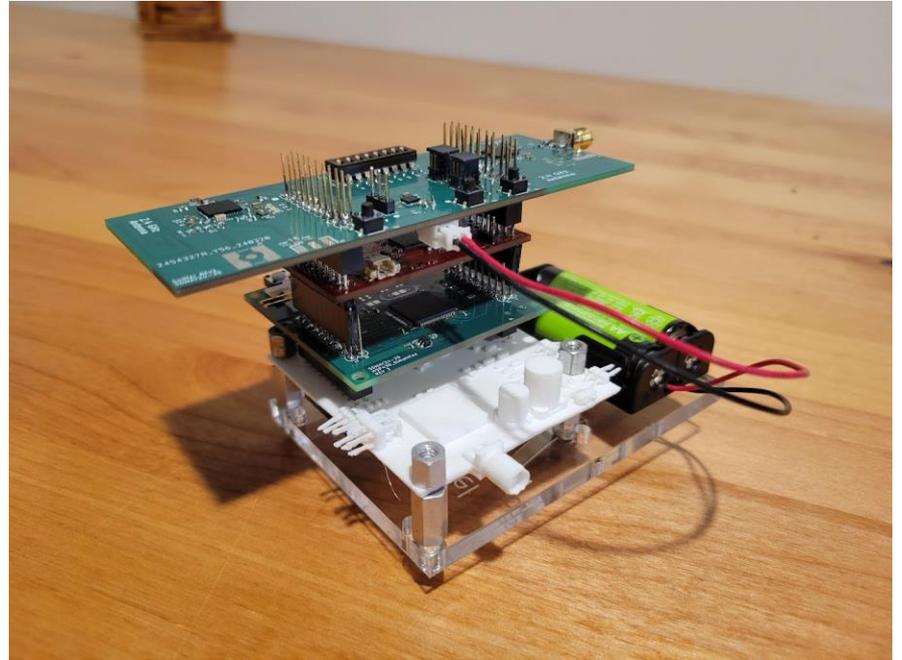
- Real Time Operating System
- Multiple Code bases
- Multi-threading
- Interrupt based programming

Integration Challenges

- CC1352 Revision with Errata
- CC1352 breaking due to clock issues

Future Work

- Integrating more nodes into the communication network.
- More rigorous load testing to ensure no packet loss
- Integrate project with researcher's testbed



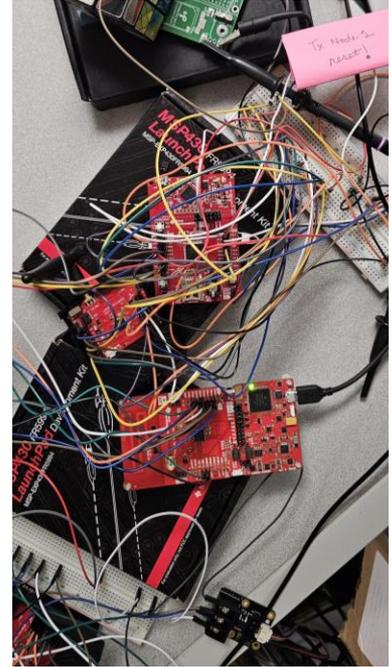
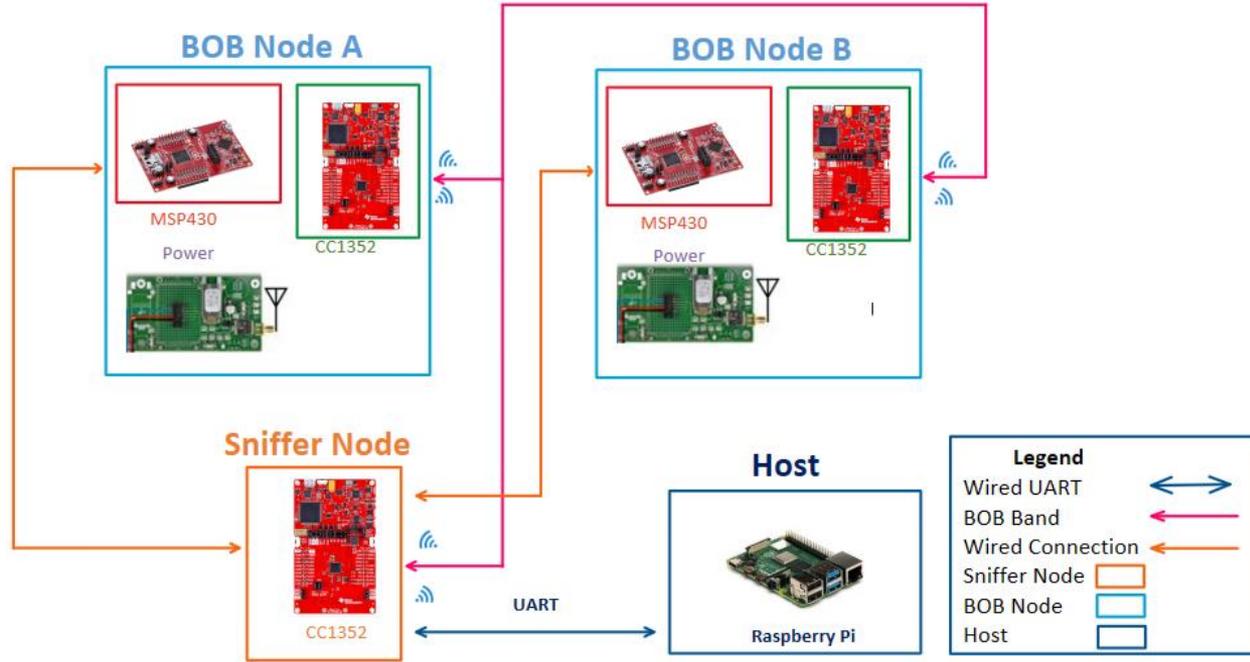


Back-up Slides

Literature Study

- "Experimental Study of Lifecycle Management Protocols for Batteryless Intermittent Communication"[2]
- "Toward a Shared Sense of Time for a Network of Batteryless, Intermittently-powered Nodes"[3]
- "Reliable Timekeeping for Intermittent Computing"[4]

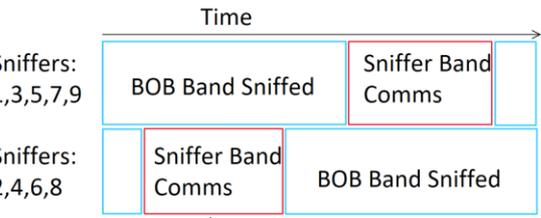
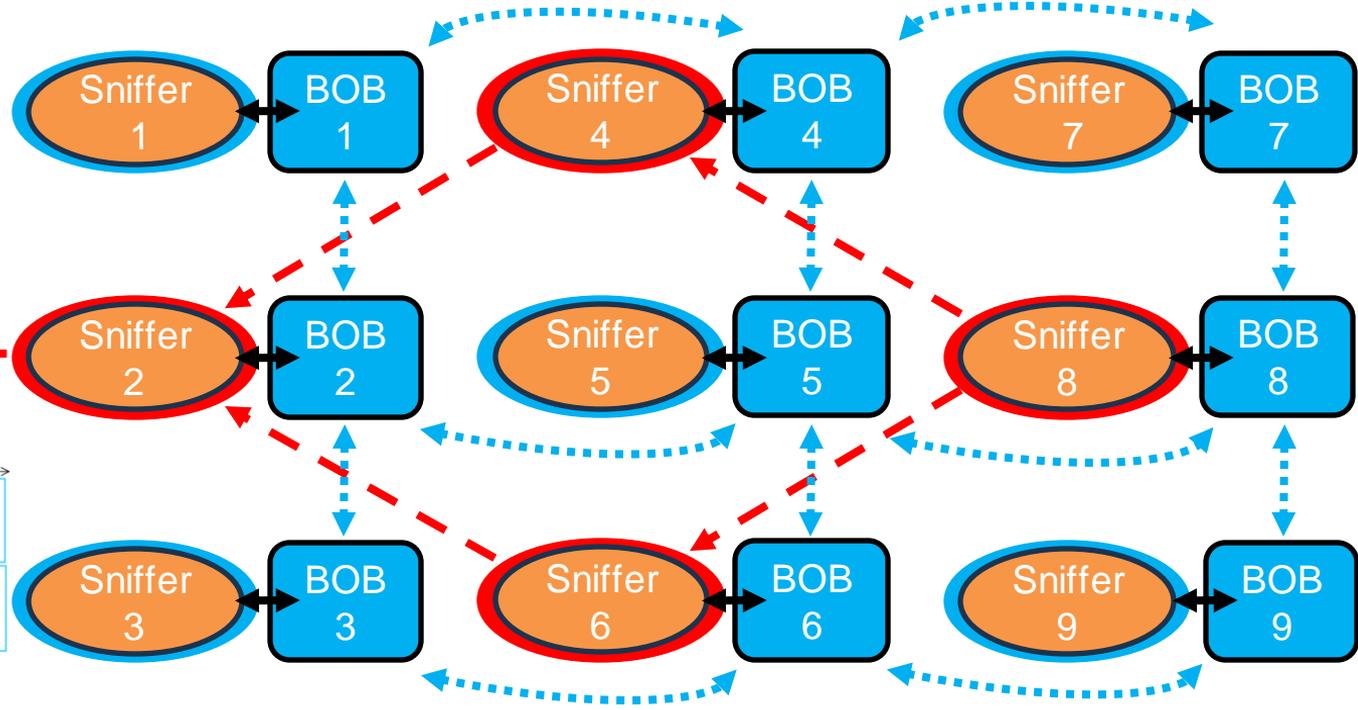
Current Design



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System Design

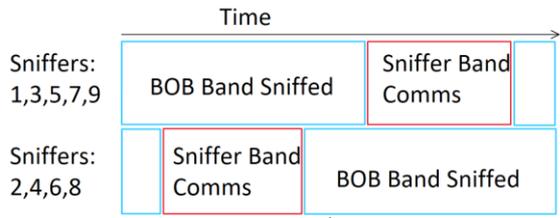
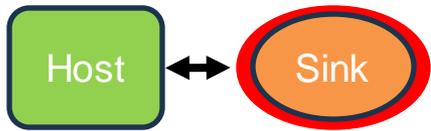
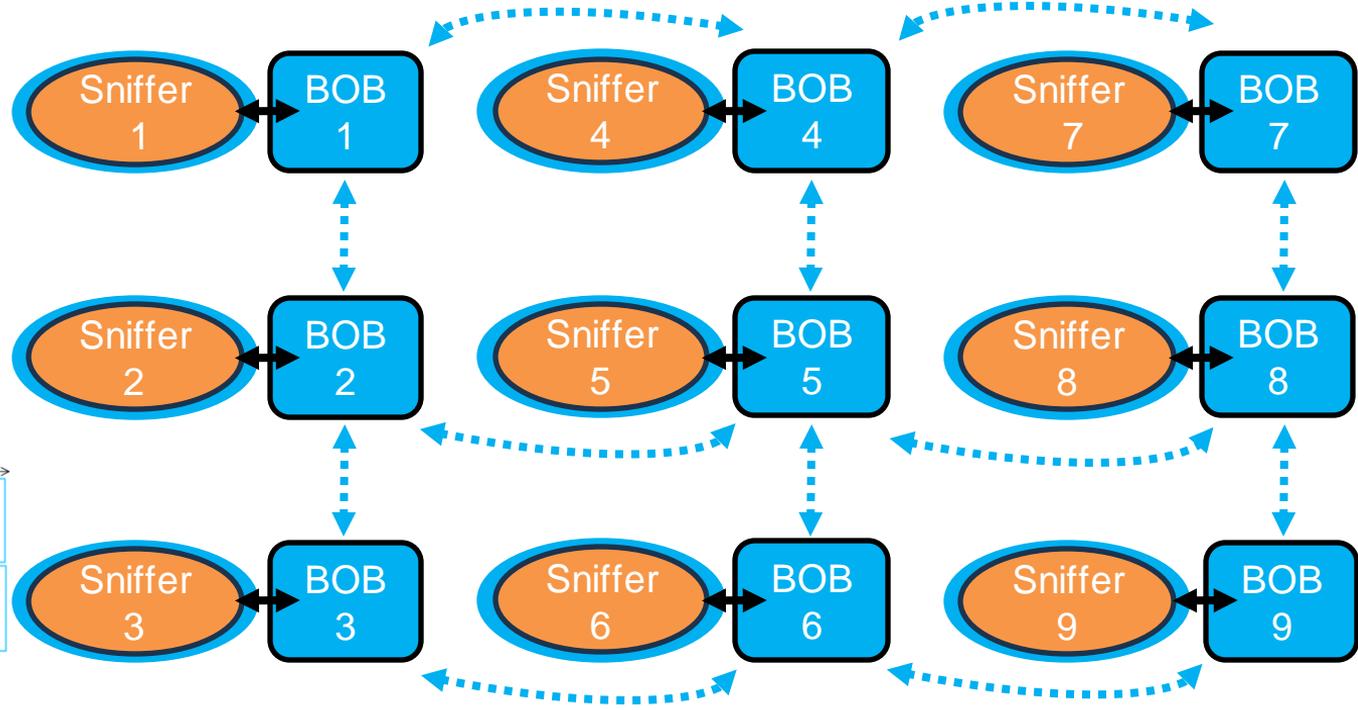
- ↔ Wired Connection
- ◀ Sink Band Comm. (2.4GHz)
- ↕ BOB Communication (Sub 1GHz)
- Listening to BOB Band
- Communicating on Sink Band



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System Design

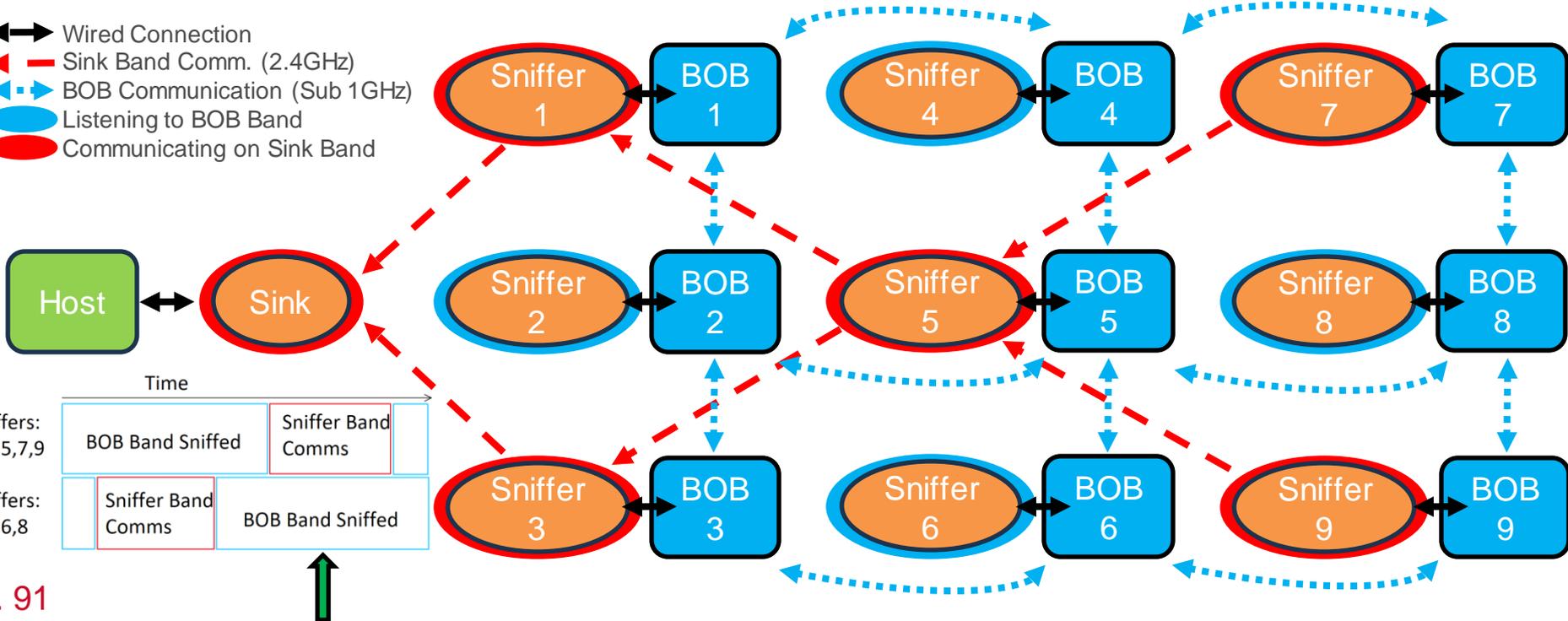
- ↔ Wired Connection
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System Design

- ↔ Wired Connection
- Sink Band Comm. (2.4GHz)
- ↔ BOB Communication (Sub 1GHz)
- Listening to BOB Band
- Communicating on Sink Band



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Hardware Cost Estimates

Cost for Single Board										
Item #	Designator	Manufacturer	Mfg Part #	Description / Value	Package	Supplier	Link	Qty	Cost	Total Cost
1	U1	GLF Integrated Power	GLF1111	Power Switch/Driver P-Channel 2A	SOT-23-5L	DigiKey	https://www.digikey.com/product-detail/en/1005XSR1A104M050B/1005XSR1A104M050B	1	0.33	0.33
2	C1, C2	Samsung Electro-Mechanics	CL05A104KA5N9NC	CAP CER 0.1UF 25V X5R 0402	0402	DigiKey	https://www.digikey.com/product-detail/en/SSW-110-03-G-D/SSW-110-03-G-D	2	0.01	0.02
3	J1	Samtec Inc.	SSW-110-03-G-D	CONN RCPT 20POS 0.1 GOLD PCB	-	DigiKey	https://www.digikey.com/product-detail/en/22122024/22122024	2	3.89	7.78
4	J2	Molex	22122024	TH, Right Angle 2 position 0.100" (2.54mm)	-	DigiKey	https://www.digikey.com/product-detail/en/RMCFO805ZTOR00/RMCFO805ZTOR00	1	0.77	0.77
5	R1	Stackpole Electronics	RMCFO805ZTOR00	RES 0 OHM JUMPER 1/8W 0805	0805	DigiKey	https://www.digikey.com/product-detail/en/SSW-110-23-G-D/SSW-110-23-G-D	1	0.018	0.018
6	-	-	-	Board Fabrication	-	JLPCB	-	1	3.892	3.892
									Total Cost	12.48

Breakout Board
PCB Total Cost (5 boards): \$20

Cost Per Breakout Board

Cost for single board										
Item #	Designator	Manufacturer	Mfg Part #	Description / Value	Package	Supplier	Link	Qty	Cost	Total Cost
1	U1	GLF Integrated Power	GLF1111	Power Switch/Driver P-Channel 2A	SOT-23-5L	DigiKey	https://www.digikey.com/product-detail/en/1005XSR1A104M050B/1005XSR1A104M050B	1	0.33	0.33
2	C1, C2, C3, C4, C10, C11	TDK Corporation	C1005XSR1A104M050B	CAP CER 0.1UF 10V X5R 0402	0402	DigiKey	https://www.digikey.com/product-detail/en/SSW-110-03-G-D/SSW-110-03-G-D	6	0.021	0.126
3	J2	Samtec Inc.	SSW-110-03-G-D	CONN RCPT 20POS 0.1 GOLD PCB	-	DigiKey	https://www.digikey.com/product-detail/en/22122024/22122024	2	3.89	7.78
4	J3	Molex	22122024	TH, Right Angle 2 position 0.100" (2.54mm)	-	DigiKey	https://www.digikey.com/product-detail/en/22122024/22122024	1	0.64	0.64
5	C6, C7	TDK Corporation	C1005COG1H220J050BA	CAP CER 22PF 50V COG 0402	0402	DigiKey	https://www.digikey.com/product-detail/en/CL05A104KA5N9NC/CL05A104KA5N9NC	2	0.047	0.094
6	C12	TDK Corporation	C1005X7R1H102K050BA	CAP CER 1000PF 50V X7R 0402	0402	DigiKey	https://www.digikey.com/product-detail/en/GRM155R61A106ME11C/GRM155R61A106ME11C	1	0.051	0.051
7	C13	Murata Electronics	GRM155R61A106ME11C	CAP CER 10UF 10V X5R 0402	0402	DigiKey	https://www.digikey.com/product-detail/en/PRPC007SBA-M71RC/PRPC007SBA-M71RC	1	0.091	0.091
8	J1	Sullins Connector Solutions	PRPC007SBA-M71RC	CONN HEADER R/A 7POS 2.54MM	-	DigiKey	https://www.digikey.com/product-detail/en/FC-135R-32/FC-135R-32	1	0.191	0.191
9	Q1	EPSON	FC-135R 32.7680KA-A0	CRYSTAL 32.7680KHZ 12.5PF SMD	-	DigiKey	https://www.digikey.com/product-detail/en/RC0402JR-070RL/RC0402JR-070RL	1	0.7	0.7
10	R1, R2, R3, R4, R5, R6, R7	YAGEO	RC0402JR-070RL	RES 0 OHM JUMPER 1/16W 0402	0402	DigiKey	https://www.digikey.com/product-detail/en/MSP430FR594IPN/MSP430FR594IPN	17	0.0045	0.0765
11	R18	YAGEO	RC0402FR-0747KL	RES 47K OHM 1% 1/16W 0402	0402	DigiKey	https://www.digikey.com/product-detail/en/60900213421/60900213421	1	0.015	0.015
12	U2	Texas Instruments	MSP430FR594IPN	IC MCU 16BIT 256KB FRAM 80LQFP	-	Mouser	https://www.digikey.com/product-detail/en/TL59NF160Q/TL59NF160Q	1	11.27	11.27
13	Q2	DNP	-	-	-	-	-	-	-	-
14	-	Würth Elektronik	60900213421	JUMPER W/TEST PNT 1X2PINS 2.54MM	-	DigiKey	https://www.digikey.com/product-detail/en/TL59NF160Q/TL59NF160Q	1	0.31	0.31
15	S1,S2	E-Switch	TL59NF160Q	SWITCH TACTILE SPST-NO 0.05A 12V	-	DigiKey	https://www.digikey.com/product-detail/en/SSW-110-23-G-D/SSW-110-23-G-D	2	0.284	0.568
16	J2 (trying another comp)	Samtec Inc.	SSW-110-23-G-D	CONN RCPT 20POS 0.1 GOLD PCB	-	DigiKey	https://www.digikey.com/product-detail/en/SSW-110-23-G-D/SSW-110-23-G-D	0	5.71	0
17	-	-	-	PCB Fabrication	-	JLPCB	-	1	4.96	4.96
									Total Cost	27.2026

Cost Per MSP Simplified Single Board Cost

MSP Simplified PCB
Total Cost (10 boards): \$31

Approximate Cost Per Board

Breakout Board	~\$17
MSP Simplified	~\$31

Hardware Cost Estimates

Total Senior Design Hardware Costs		
Order #	Order Description	Cost
1	Breakout Board PCB & Part Ord	37.83
2	MSP REV 1 PCB & Part Order	203.8
3	MSP REV 2 PCB & Part Order	30.8
4	Sniffer REV 1 PCB & Part Order	611.88
5	Battery Order	112.05
6	Extra Component Order	29.29
	Total Cost:	1025.65

Stack Pinouts

SD)

Table 1				Table 2						
GPIO	MSP430	CC1352 radio	I/O (as seen from the msp430)	GPIO	MSP430	CC1352 radio	CC1352 sniffer	Harvester	I/O	
Data Received	P5.0	DIO22	I	Powered ON	P7.7		DIO25	DIO28		O
Transmit Request	P5.1	DIO3	O	Event Gen	P7.4		DIO26	DIO29		I
Transmit Done	P5.2	DIO24	I	Testbed Reset	P7.5		DIO27	DIO30		I
SPI Master Ready	P5.3	DIO19	O	Easylink Tx		DIO25	DIO24	DIO21		
SPI Slave Ready	P5.4	DIO7	I	Event drop	P7.6		DIO9	DIO8		O
FRAM Written	P5.5	DIO11	O	Reset	P7.3			Reset		I
Power radio	P1.4									
SPI MOSI	P6.4	DIO9								
SPI MISO	P6.5	DIO8								
SPI CLK	P6.6	DIO10								
SPI SS	P6.7	DIO20	O							

Note currently in our setup we have only one sniffer for two msp430 nodes. I/O are defined with respect to msp430 node
Code needs update

Figure 12: Plan to Create Extra NC Pins on the CC1352R Development Board

Stack Pinouts

MSP Board Pinout								
Pin #	Func	Pin #	Func		Pin #	Func	Pin #	Func
1	3V3 to CC	21	3V3		40	P5.4	20	GND
2	GPIO	22	GND		39	GPIO	19	P5.1
3	GPIO	23	NC		38	P6.7	18	P5.5
4	GPIO	24	GPIO		37	P3.5	17	GPIO/EN
5	P5.0	25	GPIO		36	GPIO	16	NC
6	P5.2	26	GPIO		35	GPIO	15	P6.4
7	P6.6 (SPI)	27	GPIO		34	RST_MSP	14	P6.5
8	P1.0	28	P7.3		33	P1.1	13	P1.6
9	P7.4	29	P7.5		32	P1.7	12	P2.6
10	P7.6	30	P7.7		31	P2.5	11	GPIO

Figure 14: MSP Simplified Pinout

Stack Pinouts

Harvester Board Pinout							
Pin #	Func	Pin #	Func	Pin #	Func	Pin #	Func
1	NC	21	3V3	40	P5.4	20	GND
2		22	GND	39		19	P5.1
3		23	NC	38	P6.7	18	P5.5
4		24		37	P3.5	17	
5	P5.0	25		36		16	NC
6	P5.2	26		35		15	P6.4
7	P6.6	27		34		14	P6.5
8	P1.0	28	P7.3	33	P1.1	13	P1.6
9	P7.4	29	P7.5	32	P1.7	12	P2.6
10	P7.6	30	P7.7	31	P2.5	11	

Figure 15: Power Harvester Pinout

LIPO Cost Estimate (Slightly Outdated)

Item	Cost per Item	Quantity	Total Cost
LIPO	\$5.00	10	\$50.00
Battery Mount	\$3.00	10	\$30.00
Protection/Management ICs	\$0.50	10	\$5.00
Charger ICs and parts	\$1.00	10	\$10.00
Charger PCB	\$15.00	1	\$15.00

Cost per board: \$11.00

Updated cost per board (no
charging board): \$9.5

Time Skew Analysis

CC1352 clock was ran with constant time reporting, compared to real-time clock

Skew ended up $> .005\%$, $.01\%$ between any given 2 nodes

Two nodes skewing in opposite directions: take 50 seconds to skew by 5 ms

Prototype Implementations - ????

No Transmit	Min	Max	Mean
Power (mW)	4.6707	7.5945	5.9900
Current (mA)	1.4154	2.3014	1.8152

Transmit every 5ms	Min	Max	Mean
Power (mW)	4.6707	7.5945	5.9900
Current (mA)	1.4154	2.3014	1.8152

$$P_{avg} = 0.5(5.99) + 0.5(26.09) = 16.04mW$$

$$E_{wk} = P_{avg}(7)(24)(60)(60) = 9.701kJ$$

Prototype Implementations - ????

No Transmit	Min	Max	Mean
Power (mW)	4.6707	7.5945	5.9900
Current (mA)	1.4154	2.3014	1.8152

Transmit every 5ms	Min	Max	Mean
Power (mW)	4.6707	7.5945	5.9900
Current (mA)	1.4154	2.3014	1.8152

$$capacity - needed = (0.5(I_{normal}) + 0.5(I_{trans,5ms}))(7)(24)$$

$$capacity - needed = ((0.5)(1.8152) + (0.5)(7.9060))(7)(24) = 816.581 mAh$$

$$capacity - needed = \left(\frac{P_{avg}}{V_{supplied}}\right)(7)(24) = \frac{2695}{V_{supplied}} mAh$$

+10% buffer

References

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